

ABSTRACT OF THE DISCLOSURE

Probes 1 for testing and outer connecting terminals 14a are electrically connected to a test socket for semiconductor devices. In use of a connecting sheet, 5 fabricated by an elastically deformative insulating member and electrodes 202, flexibility is given, and good electrical contacts are obtainable. Further, because the connecting sheet 2 is exchangeable, contacting capability is recovered by exchange when solder debris is adhered 10 and deposited to increase contact resistances. Accordingly, even though there is scattering of the heights of the outer connecting terminals, good electrical contact with the probes is obtainable, and even though the solder debris of the outer connecting 15 terminals is adhered and deposited as a result of repeated usage, tests can be continuously conducted, wherein the test socket for semiconductor devices has good maintenance capability.